

Title (en)
BATH FOR GOLD ELECTRODEPOSITION

Title (de)
BAD FÜR GALVANISCHEN GOLDNIEDERSCHLAG

Title (fr)
BAIN POUR DEPOT ELECTROLYTIQUE D'OR

Publication
EP 1520063 A1 20050406 (FR)

Application
EP 03729763 A 20030620

Priority
• EP 03729763 A 20030620
• CH 0300400 W 20030620
• EP 02405558 A 20020704

Abstract (en)
[origin: EP1378590A1] A bath for the electrolytic deposition of gold comprises, in solution in water, a gold sulfite, a grain refiner, an inhibitor and a conducting salt. The grain refiner is chosen from soluble compounds of bismuth, tin, tellurium and selenium. Preferred Features: The soluble bismuth compound is a soluble complex of ammonium citrate and bismuth. The inhibitor contains a derivative of phosphonic acid. The conducting salt is ammonium sulfite. The bath may also contain 20-100 g/liter, preferably 50 g/liter, of amidosulphonic acid.

IPC 1-7
C25D 3/48

IPC 8 full level
C25D 3/48 (2006.01)

CPC (source: EP)
C25D 3/48 (2013.01)

Cited by
KR101464343B1

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DOCDB simple family (publication)
EP 1378590 A1 20040107; AT E307918 T1 20051115; AU 2003240347 A1 20040123; DE 60302074 D1 20051201; DE 60302074 T2 20060713; EP 1520063 A1 20050406; EP 1520063 B1 20051026; ES 2252673 T3 20060516; WO 2004005589 A1 20040115

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